

MECHANICAL CASE OUTLINE

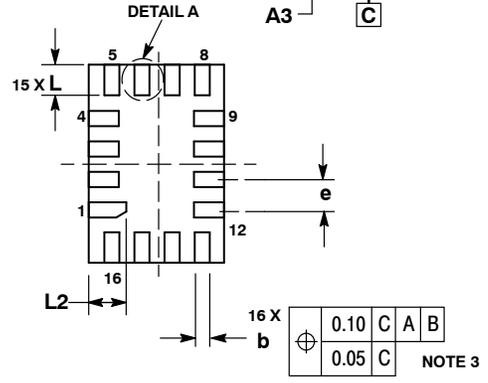
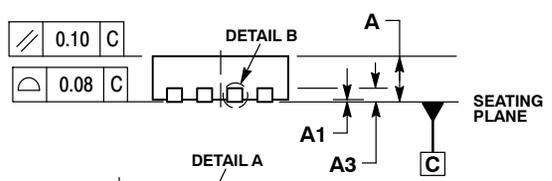
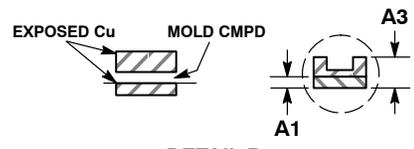
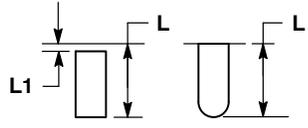
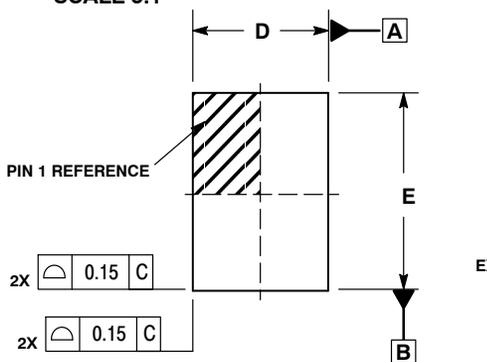
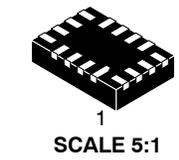
PACKAGE DIMENSIONS

ON Semiconductor®



WQFN16, 1.8x2.6, 0.4P CASE 488AP-01 ISSUE B

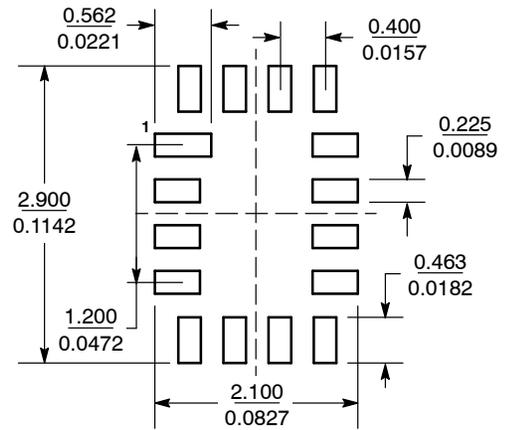
DATE 25 JUN 2008



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS
 3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.
 4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
 5. EXPOSED PADS CONNECTED TO DIE FLAG. USED AS TEST CONTACTS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.70	0.80
A1	0.00	0.050
A3	0.20 REF	
b	0.15	0.25
D	1.80 BSC	
E	2.60 BSC	
e	0.40 BSC	
L	0.30	0.50
L1	0.00	0.15
L2	0.40	0.60

MOUNTING FOOTPRINT



SCALE 20:1 (mm/inches)

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	WQFN16, 1.8 X 2.6, 0.4P	PAGE 1 OF 2

